



日本電子機械工業会規格

Standard of Electronic Industries Association of Japan

EIAJ ED-7311-4A

**集積回路パッケージ個別規格
(1.27mmピッチ T-BGA)**

**Standard of integrated circuits package
[Tape Ball Grid Array 1.27mm pitch (T-BGA)]**

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作 成

半導体パッケージ標準化委員会

Technical Standardization Committee on Semiconductor
Device Package

発 行

社団法人 日本電子機械工業会
Electronic Industries Association of Japan

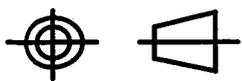
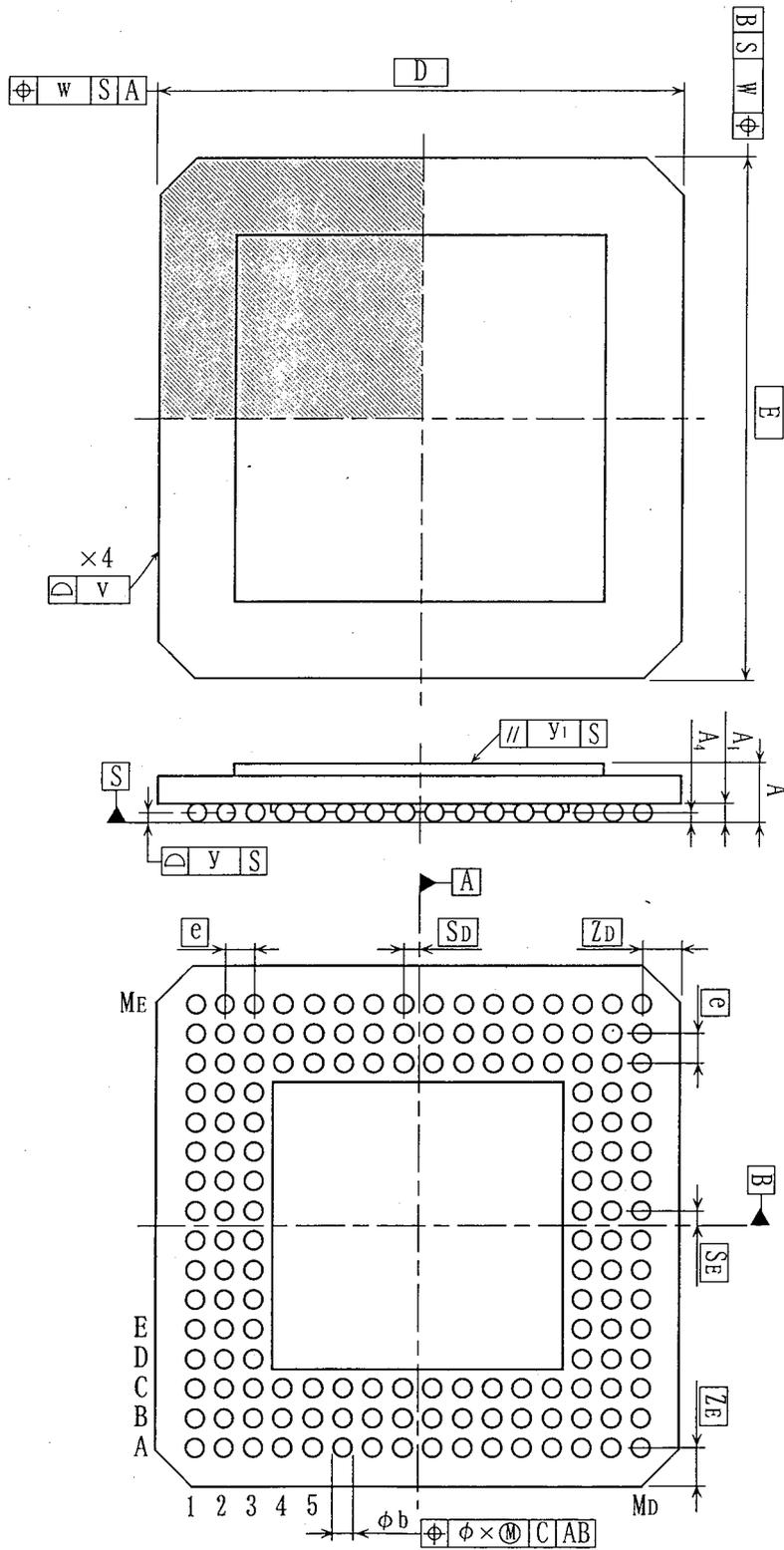
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EIAJ STANDARD
PACKAGE OUTLINE DRAWING

SHEET
1/13

PACKAGE NAME
T-BGA(1.27mm pitch)

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IC-7315-001